ASSOCIATION CONNECT: ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information			
upplier Inform				·				,					
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2024-05-14			
Contact Name		Title	Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Reques	Requester Item Number Mfr Ite		ber Mfr Ite	em Name		Effective Date Version Manufacturing Site		Manufacturing Site	W	eight*	UOM	Unit Type	
		NRVHP420MF	FDT1G 200V/2	200V/2A PUF DFN-8		2024-05-14		N	MY1		.49	mg	Each
Ianufacturing	g Proccess Informatio	on											
Terminal Plating / Grid Array Material Te			Germinal Base Alloy J-STD-020 MSI		20 MSL Rating	Peak Process Body Temperatur		e Max Time at Peak	Temperatur	e Numbe	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed		CU Allo	CU Alloy 1			260	C 30		seconds	3			
omments													
vel 1 - maximum	time at peak temperature	e during soldering	g is 10-30 second	ds									
or more informat	tion regarding material co	omposition please	refer to page 3	}									

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.34	mg	Supplier	Zinc (Zn)	7440-66-6		0.0004	mg
			Supplier	Iron (Fe)	7439-89-6		0.008	mg
			Supplier	Copper (Cu)	7440-50-8		0.3315	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach Solder	3.08	mg	Supplier	Silver (Ag)	7440-22-4		0.077	mg
			A	Lead (Pb)	7439-92-1	7a	2.849	mg
			Supplier	Tin (Sn)	7440-31-5		0.154	mg
Lead Frame	37.39	mg	Supplier	Silver (Ag)	7440-22-4		0.3739	mg
			Supplier	Iron (Fe)	7439-89-6		0.0374	mg
			Supplier	Copper (Cu)	7440-50-8		36.9675	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0112	mg
Mold Compound-Black	45.37	mg		Epoxy resin	proprietary data		3.4028	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1343	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.4028	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2268	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		37.2034	mg
Plating	1.56	mg	Supplier	Tin (Sn)	7440-31-5		1.56	mg
Wire Bond - Cu	0.09	mg	Supplier	Copper (Cu)	7440-50-8		0.09	mg